650 V SiC MPS[™] Diode

Silicon Carbide Schottky Diode

Features

- High Avalanche (UIS) Capability
- Enhanced Surge Current Capability
- Superior Figure of Merit Q_C/I_F
- Low Thermal Resistance
- 175 °C Maximum Operating Temperature
- Temperature Independent Switching Behavior
- Positive Temperature Coefficient of V_F
- Extremely Fast Switching Speeds

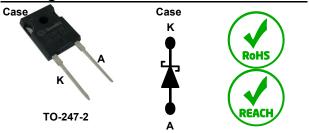
Advantages

- Low Standby Power Losses
- Improved Circuit Efficiency (Lower Overall Cost)
- Low Switching Losses
- Ease of Paralleling without Thermal Runaway
- Smaller Heat Sink Requirements
- Low Reverse Recovery Current
- Low Device Capacitance
- Low Reverse Leakage Current



V _{RRM}	=	650 V
I _{F (Tc = 135°C)}	=	92 A
Q _c	=	80 nC

Package



Applications

- Boost Diode in Power Factor Correction (PFC)
- Switched Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Motor Drives
- Freewheeling / Anti-parallel Diode in Inverters
- Solar Inverters & Wind Energy Converters
- Electric Vehicles (EV) & DC Fast Charging
- Induction Heating & Welding

Absolute Maximum Ratings (At T_c = 25 °C Unless Otherwise Stated)

Parameter	Symbol	Conditions	Values	Unit	
Repetitive Peak Reverse Voltage	V _{RRM}		650	V	
		T _C = 25 °C, D = 1	197		
Continuous Forward Current	I _F	T _C = 135 °C, D = 1	92	А	
		T _C = 160 °C, D = 1	50		
Non-Repetitive Peak Forward Surge Current, Half Sine Wave	I _{F,SM}	T _C = 25 °C, t _P = 10 ms	400	٨	
		T _C = 150 °C, t _P = 10 ms	320	A	
Repetitive Peak Forward Surge Current, Half Sine Wave	I _{F,RM}	T _C = 25 °C, t _P = 10 ms	240	٨	
		T _C = 150 °C, t _P = 10 ms	192	A	
Non-Repetitive Peak Forward Surge Current	I _{F,max}	T _C = 25 °C, t _P = 10 μs	2000	А	
i ² t Value	∫i ² dt	T _C = 25 °C, t _P = 10 ms	800	A ² s	
Non-Repetitive Avalanche Energy	E _{AS}	L = 0.6 mH, I _{AS} = 50 A	725	mJ	
Diode Ruggedness	dV/dt	V _R = 0 ~ 520 V	100	V/ns	
Power Dissipation	P _{tot}	T _C = 25 °C	800	W	
Operating and Storage Temperature	T _j , T _{stg}		-55 to 175	°C	

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Electrical Characteristics

Parameter	Symbol	Conditions		Values			llmit
	Symbol			Min.	Тур.	Max.	Unit
Diode Forward Voltage	V _F	I _F = 50 A, T _j =	I _F = 50 A, T _j = 25 °C		1.5	1.8	V
	۷F	$I_F = 50 \text{ A}, T_j =$	I _F = 50 A, T _j = 175 °C		1.8	2.2	
Reverse Current	I-	V _R = 650 V, T _j = 25 °C			1	10	μA
	I _R	V _R = 650 V, T _j =	V _R = 650 V, T _j = 175 °C		10	100	
Total Capacitive Charge	$Q_{\rm C}$		V _R = 200 V		57	57	nC
	QC	I _F ≤ I _{F,MAX} - dI _F /dt = 200 A/µs	V _R = 400 V		80		
Switching Time	ts	$T_j = 175 \ ^{\circ}C$	V _R = 200 V		< 10		ns
	Ls		V _R = 400 V		< 10		
Total Capacitance	С	V_R = 1 V, f = 1 MHz, T _j = 25 °C			2585		pF
	C	V_R = 400 V, f = 1 MHz, T _j = 25 °C			230		

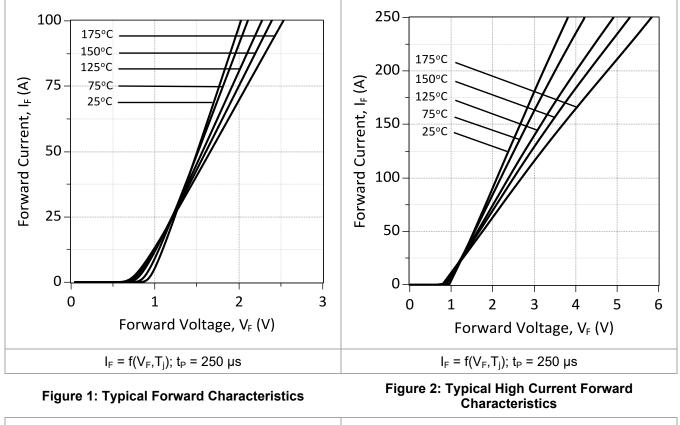
Thermal / Mechanical Characteristics

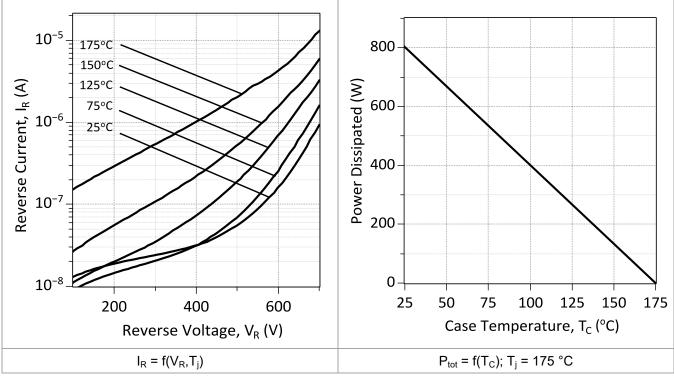
Thermal Resistance, Junction - Case	R _{thJC}		0.19	°C/W
Weight	W _T		6	g
Mounting Torque	Тм	M3 Screw	1.1	Nm





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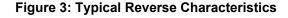
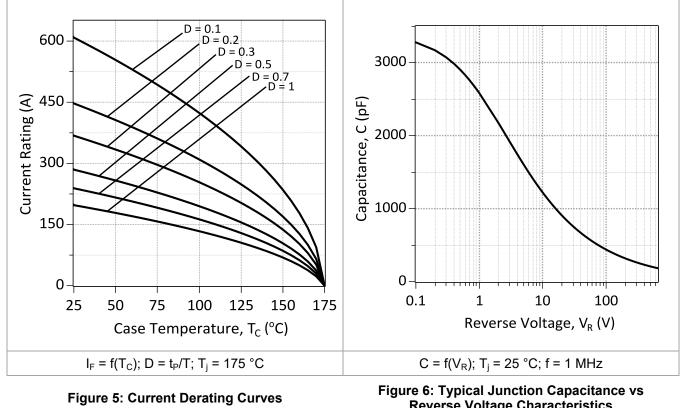
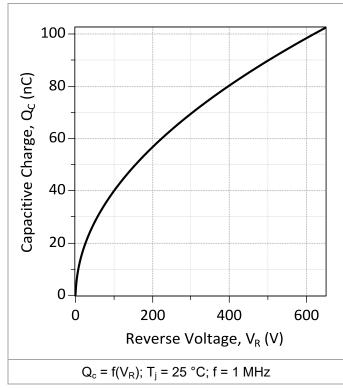


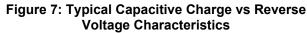
Figure 4: Power Derating Curve

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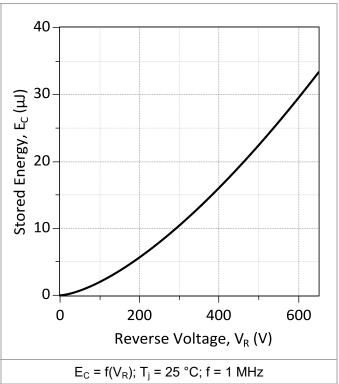


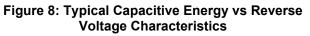




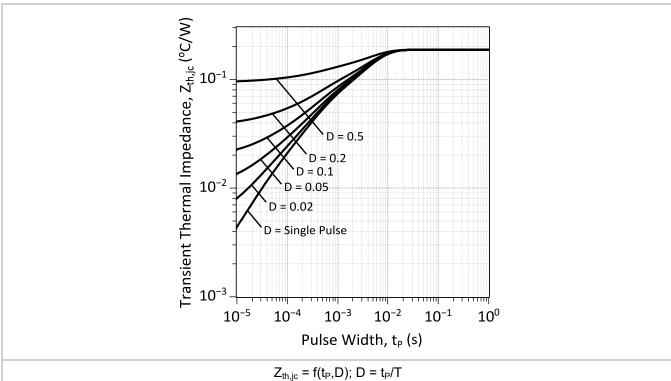




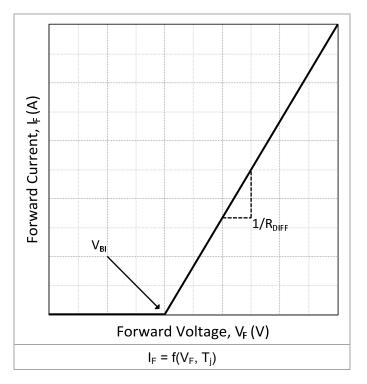




GC50MPS06-247 650 V SiC MPS[™] Diode









 $I_{F} = (V_{F} - V_{BI})/R_{DIFF} (A)$

Built-In Voltage (V_{BI}):

$$V_{BI}(T_j) = m^*T_j + n (V),$$

m = -1.26e-03, n = 1.01

Differential Resistance (R_{DIFF}):

$$\mathsf{R}_{\mathsf{DIFF}}(\mathsf{T}_{j}) = \mathsf{a}^{*}\mathsf{T}_{j}^{2} + \mathsf{b}^{*}\mathsf{T}_{j} + \mathsf{c}(\Omega);$$

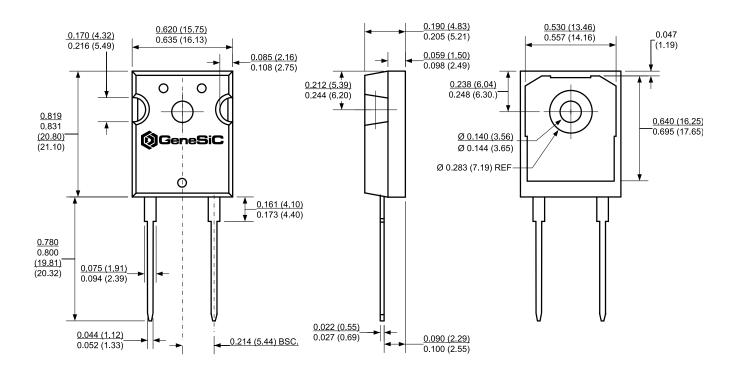
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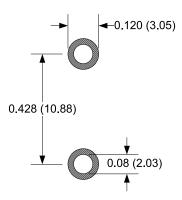
Package Dimensions

TO-247-2L

Package Outline



Recommended Solder Pad Layout



NOTE

- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
- 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

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RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS 3), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863/EU. RoHS Declarations for this product can be obtained from your GeneSiC representative.

REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a GeneSiC representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, or air traffic control systems.

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- SPICE Models: https://www.genesicsemi.com/schottky-mps
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